

# 74HC1G66; 74HCT1G66

## Single-pole single-throw analog switch

Rev. 04 — 19 December 2008

Product data sheet

### 1. General description

74HC1G66 and 74HCT1G66 are high-speed Si-gate CMOS devices. They are single-pole single-throw analog switches. The switch has two input/output pins (Y and Z) and an active HIGH enable input pin (E). When pin E is LOW, the analog switch is turned off.

The non-standard output currents are equal to those of the 74HC4066 and 74HCT4066.

### 2. Features

- Wide supply voltage range from 2.0 V to 10.0 V for the 74HC1G66
- Very low ON resistance:
  - ◆ 45  $\Omega$  (typ.) at  $V_{CC} = 4.5$  V
  - ◆ 30  $\Omega$  (typ.) at  $V_{CC} = 6.0$  V
  - ◆ 25  $\Omega$  (typ.) at  $V_{CC} = 9.0$  V
- High noise immunity
- Low power dissipation
- Multiple package options
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40$  °C to  $+85$  °C and  $-40$  °C to  $+125$  °C

### 3. Ordering information

Table 1. Ordering information

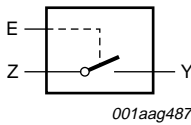
Type number	Package			
	Temperature range	Name	Description	Version
74HC1G66GW 74HCT1G66GW	$-40$ °C to $+125$ °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74HC1G66GV 74HCT1G66GV	$-40$ °C to $+125$ °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753

## 4. Marking

Table 2. Marking codes

Type number	Marking
74HC1G66GW	HL
74HCT1G66GW	TL
74HC1G66GV	H66
74HCT1G66GV	T66

## 5. Functional diagram



001aag487

**Fig 1. Logic symbol**



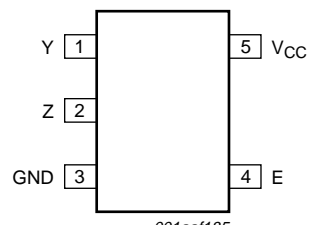
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**Fig 2. Logic diagram**

## 6. Pinning information

### 6.1 Pinning

**74HC1G66**  
**74HCT1G66**



001aaf185

**Fig 3. Pin configuration SOT353-1 and SOT753**

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
Y	1	independent input or output
Z	2	independent input or output
GND	3	ground (0 V)
E	4	enable input (active HIGH)
V <sub>CC</sub>	5	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input E	Switch
L	OFF
H	ON

[1] H = HIGH voltage level; L = LOW voltage level.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+11.0	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>SK</sub>	switch clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>SW</sub>	switch current	V <sub>SW</sub> > -0.5 V or V <sub>SW</sub> < V <sub>CC</sub> + 0.5 V	-	±25	mA
I <sub>CC</sub>	supply current		-	50	mA
I <sub>GND</sub>	ground current		-50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[2] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 and SC-74A packages: above 87.5 °C the value of P<sub>tot</sub> derates linearly with 4.0 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).<sup>[1]</sup>

Symbol	Parameter	Conditions	74HC1G66			74HCT1G66			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	10.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>SW</sub>	switch voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V
		V <sub>CC</sub> = 10.0 V	-	-	35	-	-	-	ns/V

[1] To avoid drawing V<sub>CC</sub> current out of pin Z, when switch current flows in pin Y, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into pin Z, no V<sub>CC</sub> current will flow out of terminal Y. In this case there is no limit for the voltage drop across the switch, but the voltage at pins Y and Z may not exceed V<sub>CC</sub> or GND.

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
<b>74HC1G66</b>								
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	V
		V <sub>CC</sub> = 9.0 V	6.3	4.7	-	6.3	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	V
		V <sub>CC</sub> = 9.0 V	-	4.3	2.7	-	2.7	V
I <sub>I</sub>	input leakage current	E; V <sub>I</sub> = V <sub>CC</sub> or GND						
		V <sub>CC</sub> = 6.0 V	-	0.1	1.0	-	1.0	μA
		V <sub>CC</sub> = 10.0 V	-	0.2	2.0	-	2.0	μA
I <sub>S(OFF)</sub>	OFF-state leakage current	Y or Z; V <sub>CC</sub> = 10 V; see <a href="#">Figure 4</a>	-	0.1	1.0	-	1.0	μA
I <sub>S(ON)</sub>	ON-state leakage current	Y or Z; V <sub>CC</sub> = 10 V; see <a href="#">Figure 5</a>	-	0.1	1.0	-	1.0	μA
I <sub>CC</sub>	supply current	E, Y or Z; V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>SW</sub> = GND or V <sub>CC</sub>						
		V <sub>CC</sub> = 6.0 V	-	1.0	10	-	20	μA
		V <sub>CC</sub> = 10.0 V	-	2.0	20	-	40	μA
C <sub>I</sub>	input capacitance		-	1.5	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance		-	8	-	-	-	pF

**Table 7. Static characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
<b>74HCT1G66</b>								
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	0.1	1.2	0.8	-	0.8	V
I <sub>I</sub>	input leakage current	E; V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	0.1	1.0	-	1.0	μA
I <sub>S(OFF)</sub>	OFF-state leakage current	Y or Z; V <sub>CC</sub> = 5.5 V; see <a href="#">Figure 4</a>	-	0.1	1.0	-	1.0	μA
I <sub>S(ON)</sub>	ON-state leakage current	Y or Z; V <sub>CC</sub> = 5.5 V; see <a href="#">Figure 5</a>	-	0.1	1.0	-	1.0	μA
I <sub>CC</sub>	supply current	E, Y or Z; V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 4.5 V to 5.5 V	-	1	10	-	20	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A	-	-	500	-	850	μA
C <sub>I</sub>	input capacitance		-	1.5	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance		-	8	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C.

**10.1 Test circuits**

V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = GND or V<sub>CC</sub>.

**Fig 4. Test circuit for measuring OFF-state leakage current**

V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = open circuit.

**Fig 5. Test circuit for measuring ON-state leakage current**

10.2 ON resistance

Table 8. ON resistance

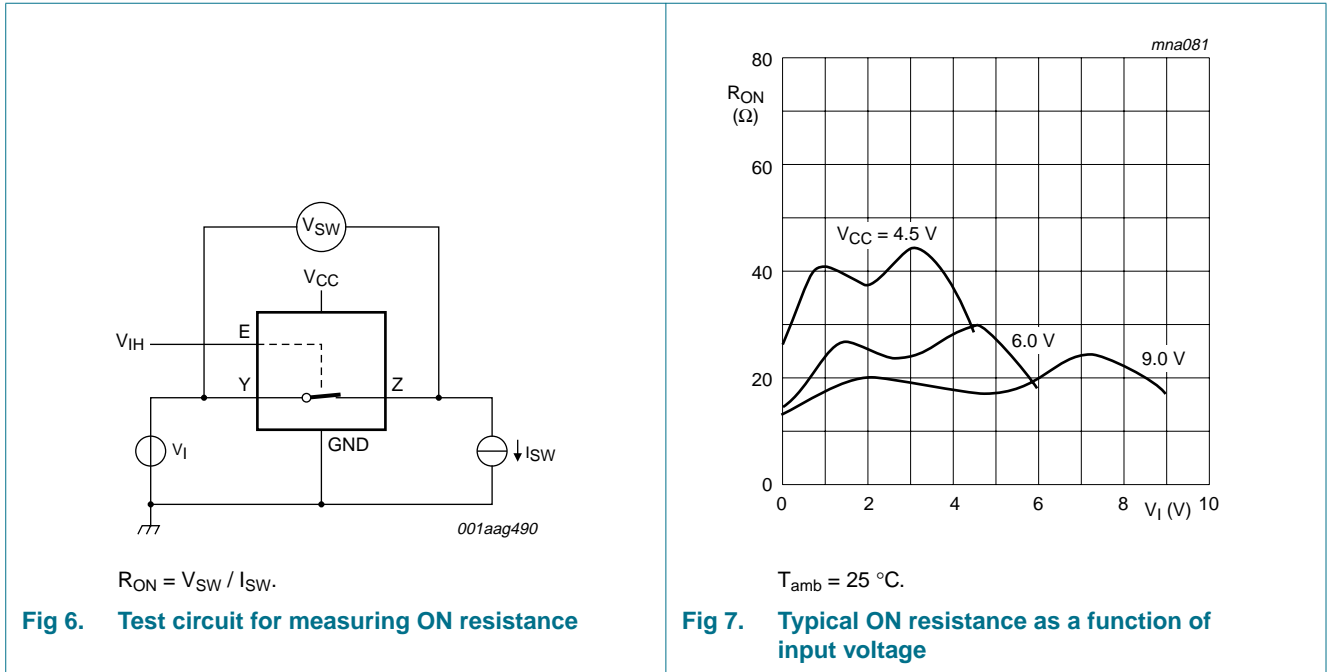
At recommended operating conditions; voltages are referenced to GND (ground 0 V); for graph see Figure 7.

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[2]</sup>	Max	Min	Max	
<b>74HC1G66<sup>[1]</sup></b>								
R <sub>ON(peak)</sub>	ON resistance (peak)	V <sub>I</sub> = GND to V <sub>CC</sub> ; see Figure 6						
		I <sub>SW</sub> = 0.1 mA; V <sub>CC</sub> = 2.0 V	-	-	-	-	-	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	42	118	-	142	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 6.0 V	-	31	105	-	126	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 9.0 V	-	23	88	-	105	Ω
R <sub>ON(rail)</sub>	ON resistance (rail)	V <sub>I</sub> = GND; see Figure 6						
		I <sub>SW</sub> = 0.1 mA; V <sub>CC</sub> = 2.0 V	-	75	-	-	-	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	29	95	-	115	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 6.0 V	-	23	82	-	100	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 9.0 V	-	18	70	-	80	Ω
		V <sub>I</sub> = V <sub>CC</sub> ; see Figure 6						
		I <sub>SW</sub> = 0.1 mA; V <sub>CC</sub> = 2.0 V	-	75	-	-	-	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	35	106	-	128	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 6.0 V	-	27	94	-	113	Ω
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 9.0 V	-	21	78	-	95	Ω
<b>74HCT1G66</b>								
R <sub>ON(peak)</sub>	ON resistance (peak)	V <sub>I</sub> = GND to V <sub>CC</sub> ; see Figure 6						
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	42	118	-	142	Ω
R <sub>ON(rail)</sub>	ON resistance (rail)	V <sub>I</sub> = GND; see Figure 6						
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	29	95	-	115	Ω
		V <sub>I</sub> = V <sub>CC</sub> ; see Figure 6						
		I <sub>SW</sub> = 1 mA; V <sub>CC</sub> = 4.5 V	-	35	106	-	128	Ω

[1] At supply voltages approaching 2 V, the ON resistance becomes extremely non-linear. Therefore it is recommended that these devices be used to transmit digital signals only, when using this supply voltage.

[2] Typical values are measured at T<sub>amb</sub> = 25 °C.

10.3 ON resistance test circuit and graphs



11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V);  $C_L = 50\text{ pF}$ ;  $R_L = 1\text{ k}\Omega$ , unless otherwise specified; For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit	
			Min	Typ <sup>[1]</sup>	Max	Min	Max		
<b>74HC1G66</b>									
$t_{pd}$	propagation delay	Y to Z or Z to Y; $R_L = \infty\ \Omega$ ; see <a href="#">Figure 8</a>							
			$V_{CC} = 2.0\text{ V}$	-	8	75	-	90	ns
			$V_{CC} = 4.5\text{ V}$	-	3	15	-	18	ns
			$V_{CC} = 6.0\text{ V}$	-	2	13	-	15	ns
			$V_{CC} = 9.0\text{ V}$	-	1	10	-	12	ns
$t_{en}$	enable time	E to Y or Z; see <a href="#">Figure 9</a>							
			$V_{CC} = 2.0\text{ V}$	-	50	125	-	150	ns
			$V_{CC} = 4.5\text{ V}$	-	16	25	-	30	ns
			$V_{CC} = 5.0\text{ V}$ ; $C_L = 15\text{ pF}$	-	11	-	-	-	ns
			$V_{CC} = 6.0\text{ V}$	-	13	21	-	26	ns
		$V_{CC} = 9.0\text{ V}$	-	9	16	-	20	ns	

**Table 9. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF;  $R_L = 1$  k $\Omega$ , unless otherwise specified;  
For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit	
			Min	Typ <sup>[1]</sup>	Max	Min	Max		
t <sub>dis</sub>	disable time	E to Y or Z; see <a href="#">Figure 9</a>		[2]					
		V <sub>CC</sub> = 2.0 V	-	27	190	-	225	ns	
		V <sub>CC</sub> = 4.5 V	-	16	38	-	45	ns	
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	ns	
		V <sub>CC</sub> = 6.0 V	-	14	33	-	38	ns	
		V <sub>CC</sub> = 9.0 V	-	12	16	-	20	ns	
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub>		[3]	-	9	-	-	pF

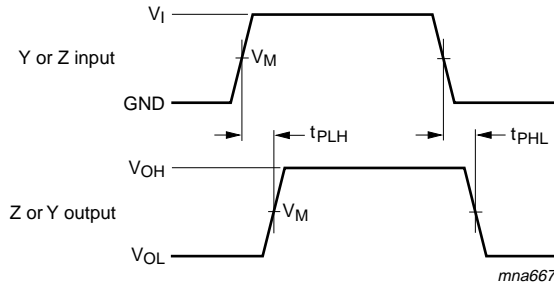
**74HCT1G66**

t <sub>pd</sub>	propagation delay	Y to Z or Z to Y; R <sub>L</sub> = ∞ $\Omega$ ; see <a href="#">Figure 8</a>		[2]					
		V <sub>CC</sub> = 4.5 V	-	3	15	-	18	ns	
t <sub>en</sub>	enable time	E to Y or Z; see <a href="#">Figure 9</a>		[2]					
		V <sub>CC</sub> = 4.5 V	-	15	30	-	36	ns	
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	12	-	-	-	ns	
t <sub>dis</sub>	disable time	E to Y or Z; see <a href="#">Figure 9</a>		[2]					
		V <sub>CC</sub> = 4.5 V	-	13	44	-	53	ns	
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	12	-	-	-	ns	
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V		[3]	-	9	-	-	pF

- [1] All typical values are measured at T<sub>amb</sub> = 25 °C.
- [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.  
t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.
- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation P<sub>D</sub> ( $\mu$ W).  
P<sub>D</sub> = C<sub>PD</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>i</sub> +  $\Sigma$  ((C<sub>L</sub> × C<sub>SW</sub>) × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) where:  
f<sub>i</sub> = input frequency in MHz;  
f<sub>o</sub> = output frequency in MHz;  
C<sub>L</sub> = output load capacitance in pF;  
C<sub>SW</sub> = maximum switch capacitance in pF (see [Table 7](#));  
V<sub>CC</sub> = supply voltage in Volt;  
 $\Sigma$  ((C<sub>L</sub> × C<sub>SW</sub>) × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.



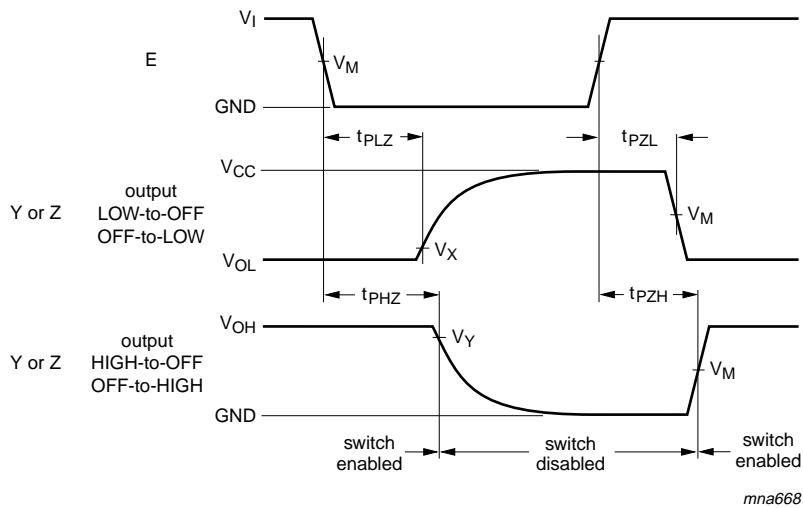
11.1 Waveforms and test circuit



Measurement points are given in [Table 10](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 8. Input (Y or Z) to output (Z or Y) propagation delays



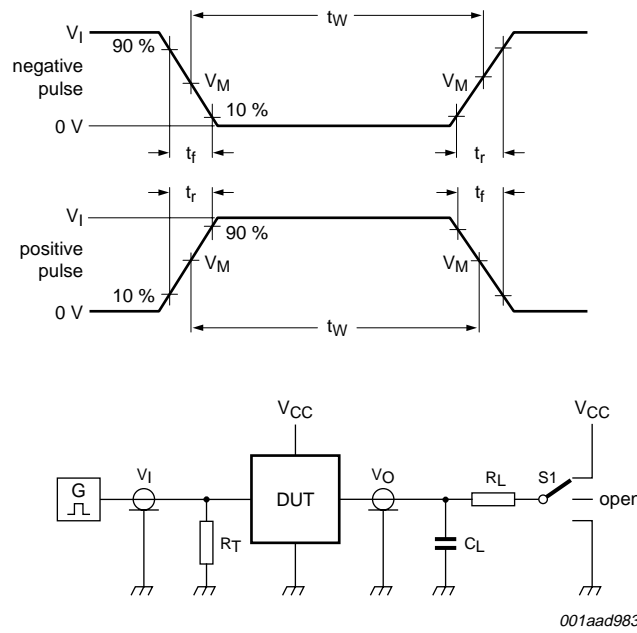
Measurement points are given in [Table 10](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 9. Enable and disable times

Table 10. Measurement points

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC1G66	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 10\%$	$V_{OH} - 10\%$
74HCT1G66	1.3 V	1.3 V	$V_{OL} + 10\%$	$V_{OH} - 10\%$



Test data is given in [Table 11](#).

Definitions for test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 10. Test circuit for measuring switching times**

**Table 11. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$ <sup>[1]</sup>	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC1G66	GND to $V_{CC}$	6 ns	50 pF, 15 pF	1 k $\Omega$ , $\infty \Omega$	open	GND	$V_{CC}$
74HCT1G66	GND to 3 V	6 ns	50 pF, 15 pF	1 k $\Omega$ , $\infty \Omega$	open	GND	$V_{CC}$

[1] There is no constraint on  $t_r, t_f$  with a 50% duty factor when measuring  $f_{max}$ .

## 11.2 Additional dynamic characteristics

**Table 12. Additional dynamic characteristics for 74HC1G66 and 74HCT1G66**

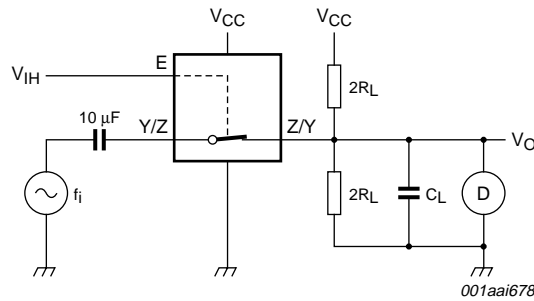
$GND = 0 V$ ;  $t_r = t_f = 6.0 ns$ ;  $C_L = 50 pF$ ; unless otherwise specified. All typical values are measured at  $T_{amb} = 25^\circ C$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
THD	total harmonic distortion	$f_i = 1 kHz$ ; $R_L = 10 k\Omega$ ; see <a href="#">Figure 11</a>				%	
		$V_{CC} = 4.5 V$ ; $V_I = 4.0 V$ (p-p)	-	0.04	-	%	
		$V_{CC} = 9.0 V$ ; $V_I = 8.0 V$ (p-p)	-	0.02	-	%	
		$f_i = 10 kHz$ ; $R_L = 10 k\Omega$ ; see <a href="#">Figure 11</a>					%
		$V_{CC} = 4.5 V$ ; $V_I = 4.0 V$ (p-p)	-	0.12	-	%	
		$V_{CC} = 9.0 V$ ; $V_I = 8.0 V$ (p-p)	-	0.06	-	%	

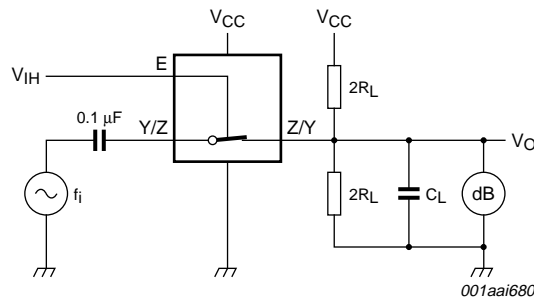
**Table 12. Additional dynamic characteristics for 74HC1G66 and 74HCT1G66 ...continued**  
*GND = 0 V;  $t_r = t_f = 6.0$  ns;  $C_L = 50$  pF; unless otherwise specified. All typical values are measured at  $T_{amb} = 25^\circ\text{C}$ .*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$f_{(-3\text{dB})}$	-3 dB frequency response	$R_L = 50 \Omega$ ; $C_L = 10$ pF; see <a href="#">Figure 12</a> and <a href="#">13</a>	-	-	-	-
		$V_{CC} = 4.5$ V	-	180	-	MHz
		$V_{CC} = 9.0$ V	-	200	-	MHz
$\alpha_{\text{iso}}$	isolation (OFF-state)	$R_L = 600 \Omega$ ; $f_i = 1$ MHz; see <a href="#">Figure 14</a> and <a href="#">15</a>	-	-	-	-
		$V_{CC} = 4.5$ V	-	-50	-	dB
		$V_{CC} = 9.0$ V	-	-50	-	dB

### 11.3 Test circuits and graphs

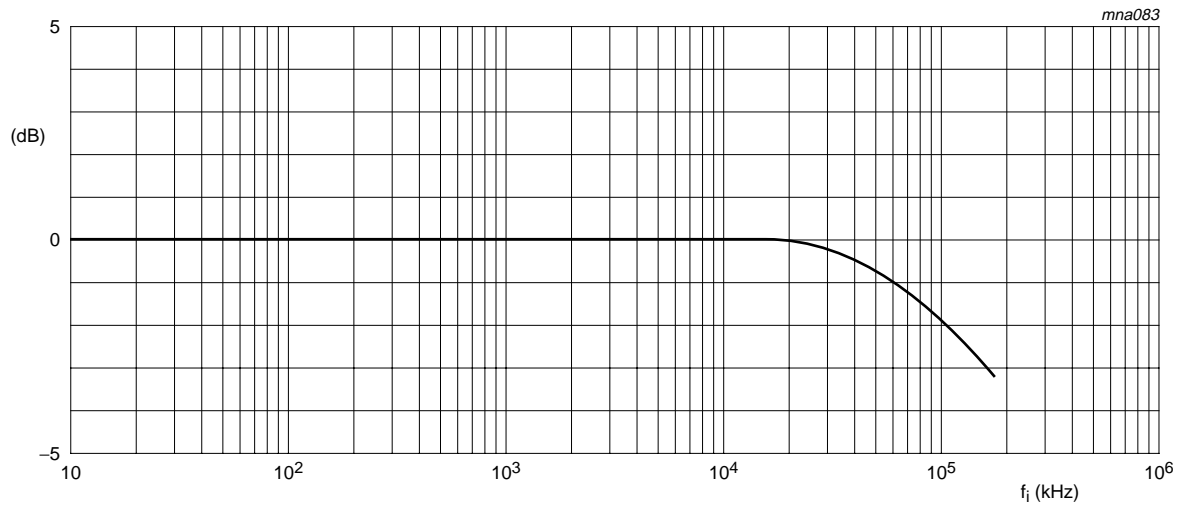


**Fig 11. Test circuit for measuring total harmonic distortion**



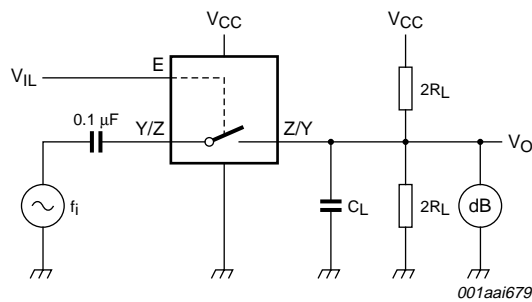
With  $f_i = 1$  MHz adjust the switch input voltage for a 0 dBm level at the switch output, (0 dBm = 1 mW into 50  $\Omega$ ). Then increase the input frequency until the dB meter reads -3 dB

**Fig 12. Test circuit for measuring the -3 dB frequency response**



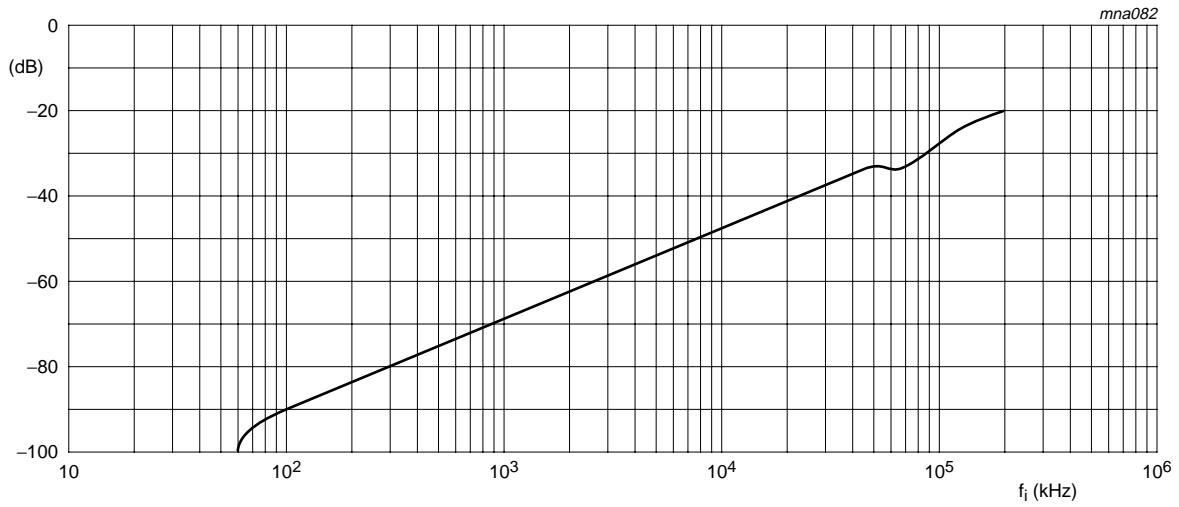
Test conditions:  $V_{CC} = 4.5\text{ V}$ ;  $GND = 0\text{ V}$ ;  $R_L = 50\ \Omega$ ;  $R_{SOURCE} = 1\text{ k}\Omega$ .

**Fig 13. Typical -3 dB frequency response**



Adjust the switch input voltage for a 0 dBm level, (0 dBm = 1 mW into 600  $\Omega$ )

**Fig 14. Test circuit for measuring isolation (OFF-state)**



Test conditions:  $V_{CC} = 4.5\text{ V}$ ;  $GND = 0\text{ V}$ ;  $R_L = 50\ \Omega$ ;  $R_{SOURCE} = 1\text{ k}\Omega$ .

**Fig 15. Typical isolation (OFF-state) as a function of frequency**

12. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

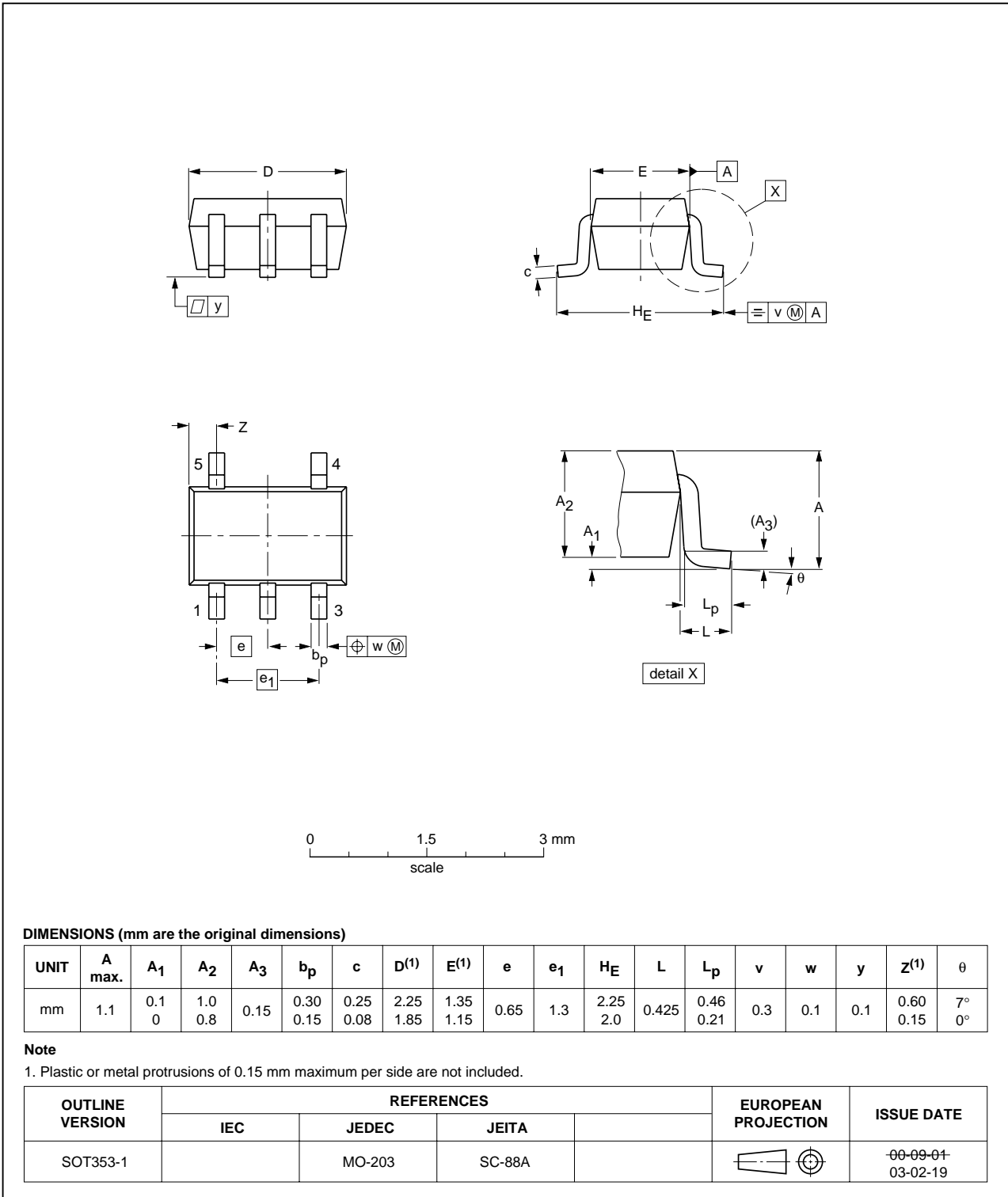


Fig 16. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

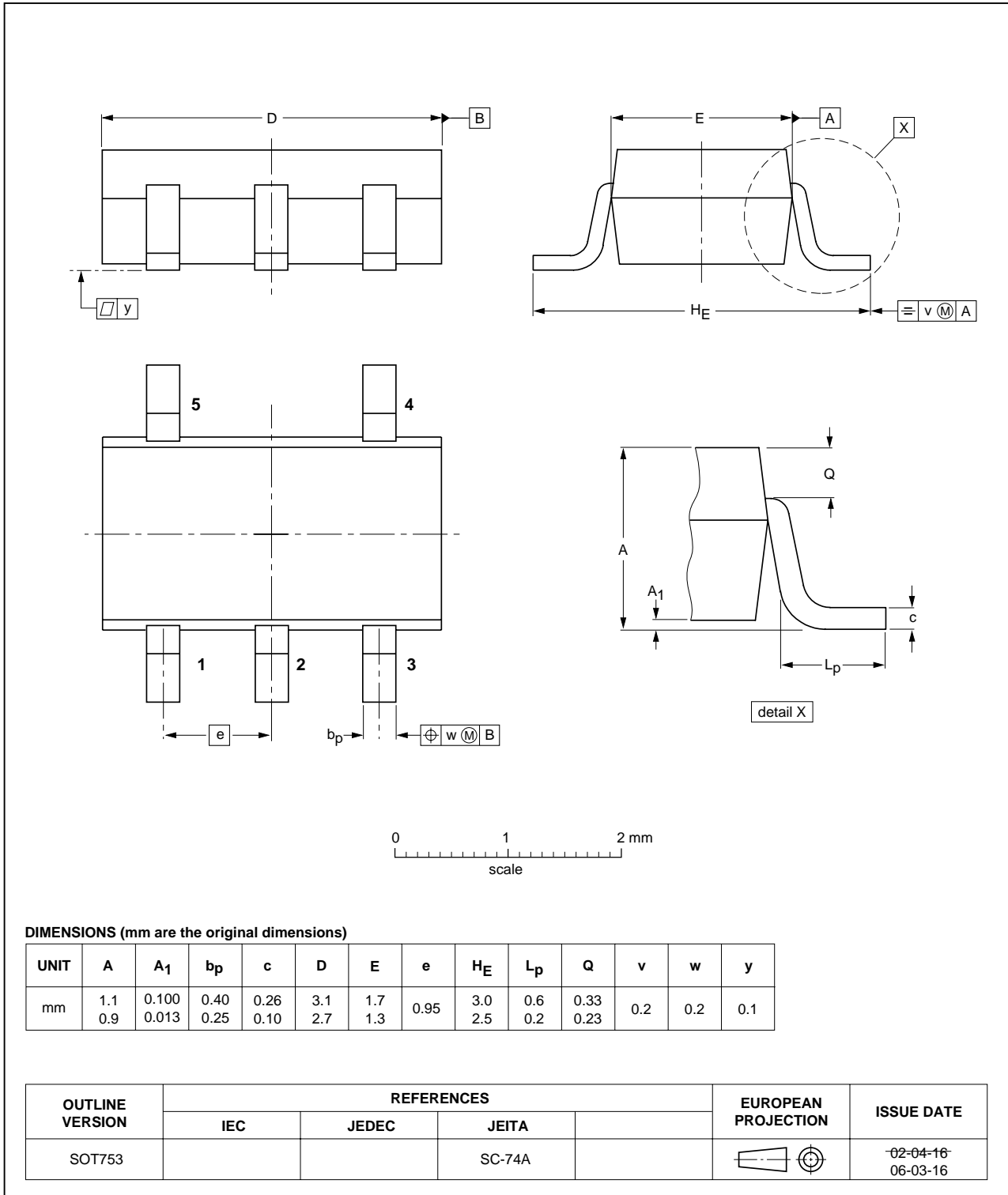


Fig 17. Package outline SOT753 (SC-74A)

## 13. Abbreviations

**Table 13. Abbreviations**

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
DUT	Device Under Test

## 14. Revision history

**Table 14. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT1G66_4	20081219	Product data sheet	-	74HC_HCT1G66_3
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Package SOT353 changed to SOT353-1 in <a href="#">Table 1</a> and <a href="#">Figure 16</a>.</li> <li>Quick Reference Data and Soldering sections removed.</li> <li><a href="#">Section 2 "Features"</a> updated.</li> </ul>			
74HC_HCT1G66_3	20020515	Product specification	-	74HC_HCT1G66_2
74HC_HCT1G66_2	20010302	Product specification	-	74HC_HCT1G66_1
74HC_HCT1G66_1	19980803	Product specification	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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